IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.

: 10/758,487

Confirmation No. 6171

Applicant(s)

: KURODA, Hirofumi

Filed

: 01/15/2004

TC/A.U.

: 2811

Examiner

: Michael J. Feely

Title

: Epoxy Resin Composition and Semiconductor Device Using Thereof

Docket No.

: 033036.070

Customer No.

: 25461

MAIL STOP ISSUE FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

TRANSMITTAL LETTER

Pursuant to Paragraph II of the Notice of Allowance and Fee(s) Due (PTOL-85), applicants submit herewith the Part B - Fee Transmittal form which was inadvertently omitted at the time the issue fee and publication fee were paid. These fees were paid online on June 8, 2006, and the payment of these fees was acknowledged by the PTO in the Electronic Acknowledgement Receipt (a copy of which is attached for convenience).

Respectfully submitted,

By: Robert G. Weilacher, Reg. No. 20,531

Dated: November 17, 2006

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